

CLAIMS

What is claimed is:

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1. A method for assembling a plurality of laser diode submodules comprising the steps of:

Preparing the submodules;

situating a substrate on a substrate carrier, the substrate having isolation grooves

10 defined therein and solder thereon between the isolation grooves;

disposing the submodules on a stacking block;

applying a vacuum to the substrate to hold it in place against the carrier;

aligning the submodules with the isolation grooves;

15 biasing together the substrate carrier and the stacking block with an elastic bi-metallic clip; and

heating the clip, block and carrier, with the substrate and submodules therein, until the solder melts and the bimetallic clip opens due to thermal expansion.

2. A method according to claim 1 wherein the step of preparing the submodules
20 comprises the steps of:

disposing a diode between two conductive preforms;

arranging the diode and preforms between parallel spacers to constitute a submodule;

placing the submodule between a conforming tool and a loading tool; and

25 heating the submodule to melt the preforms.